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(71) Applicant (for all designated States except US): **INFI-  
NEON TECHNOLOGIES AG** [DE/DE]; St.-Martin-Str.  
53, 81669 München (DE).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **OFNER, Gerald**  
[AT/DE]; Wilhelm-Busch-Str. 5, 93077 Bad Abbach (DE).  
**ZHU, Wenhui** [CN/SG]; Blk 229, #05-168, Lor 8 Toa  
Payoh, 310229 Singapur (SG). **ABERIN, Irwin** [PH/SG];  
#41 Minbu Rd., 03-00, 308179 Singapur (SG). **YEO,  
Alfred** [CN/SG]; Blk 351, #14-123, Ang Mo Kio Street  
32, 560351 Singapur (SG).

(74) Agent: **SCHWEIGER, Martin**; c/o Kanzlei Schweiger &  
PartnerKarl-, Theodor-Str. 69, 80803 München (DE).

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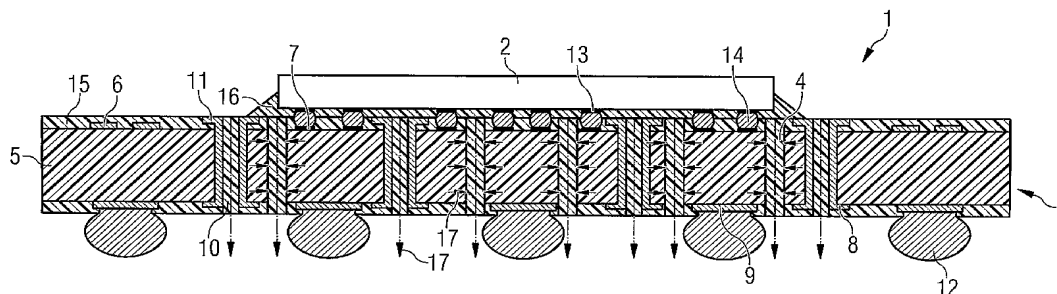
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(54) Title: SEMICONDUCTOR PACKAGE WITH PERFORATED SUBSTRATE



(57) Abstract: A semiconductor package (1; 18; 20) comprises a substrate (3; 21) and a semiconductor chip (2) which includes an active surface with a plurality of chipcontact areas (13). The chip (2) is electrically connected to the substrate (3; 21). The substrate comprises a sheet of core material (5), a plurality of upper conducting traces (6) and upper contact pads (7) on its upper surface, a second plurality of lower conductive traces (8) and external contact areas (9) on its bottom surface. A plurality of conducting vias (10) connect the conducting traces (6) and lower conducting traces (8). The substrate (3; 21) also includes a plurality of vent holes for releasing moisture (4; 22) and a layer of solder resist (15) covering the upper and lower surfaces of the substrate (3) leaving the contact areas (6 and 8) free from solder resist (15).

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